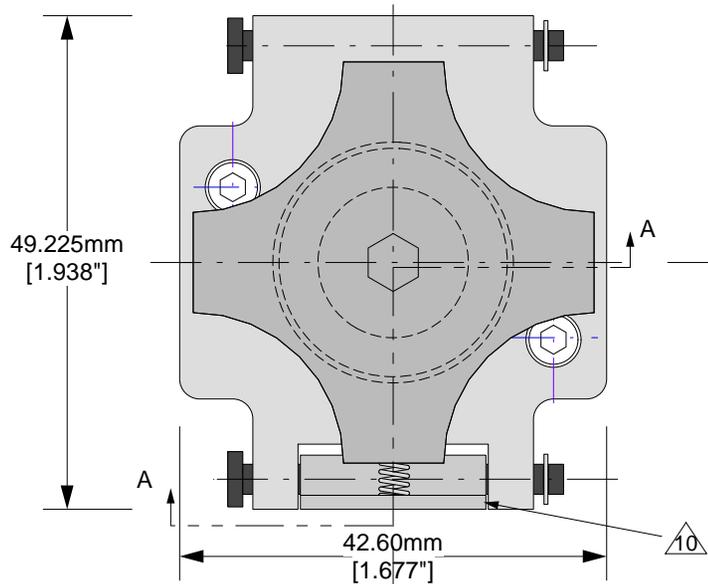
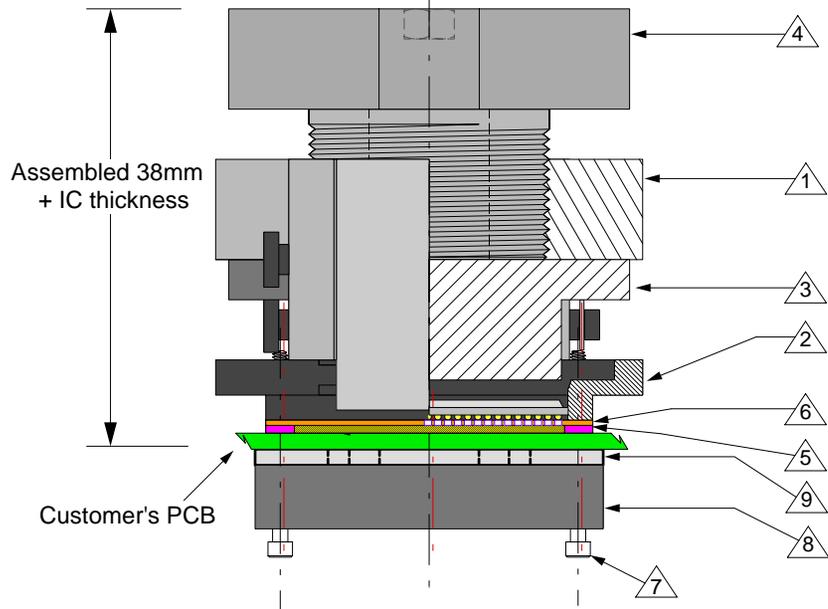


Top View



Side View
(Section AA)



Features

- Directly mounts to target PCB (needs tooling holes) with hardware
- Minimum real estate required
- Compression plate distributes forces evenly
- Clamshell lid

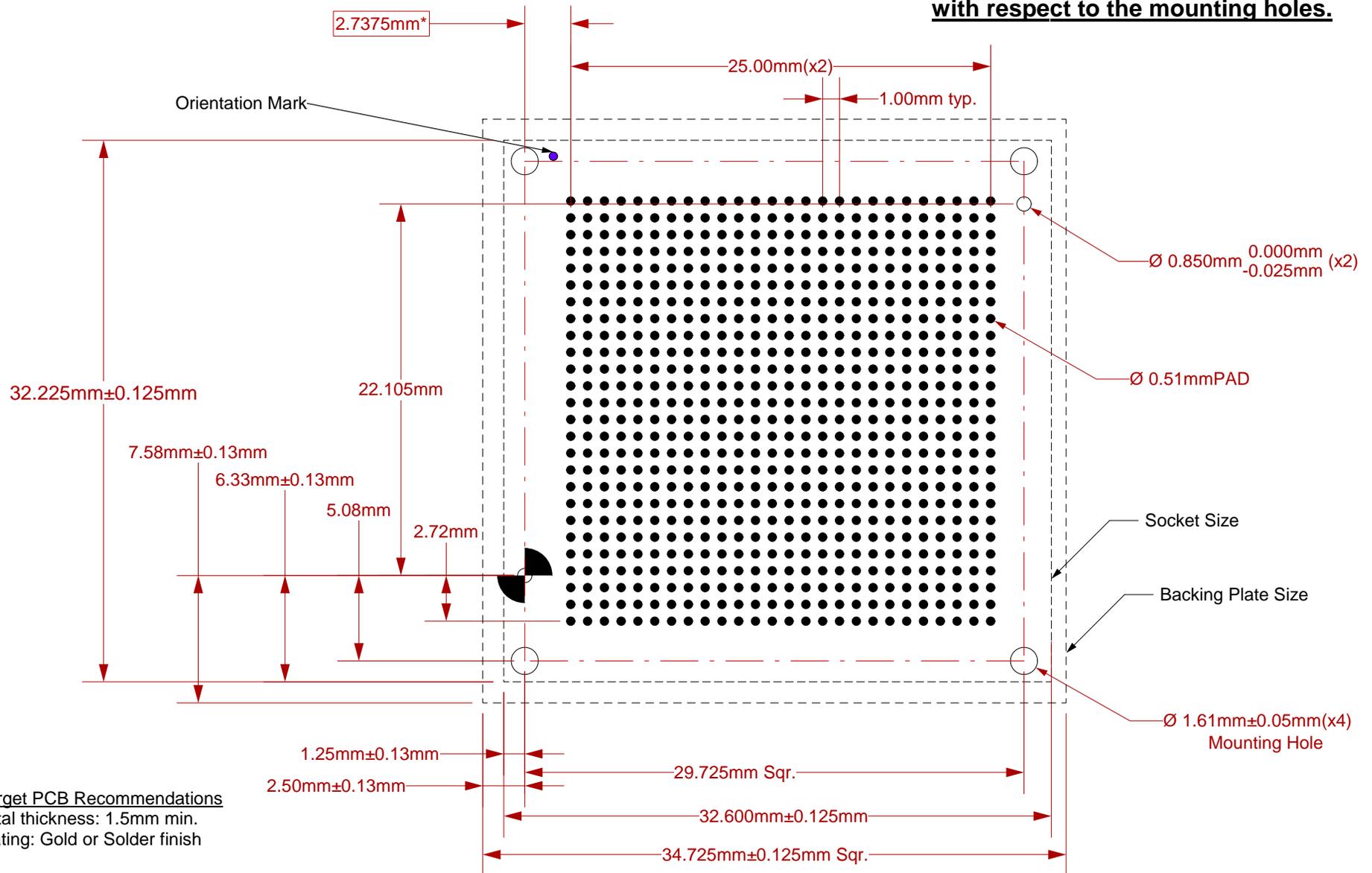
Materials:

- 1 Clam Shell Lid: Black anodized 7075 Aluminum. Height = 20 mm.
- 2 Socket Base: Black anodized 7075 Aluminum. Height = 6 mm.
- 3 Compression Plate: Black anodized 7075 Aluminum. Thickness = 12 mm.
- 4 Compression Screw: Clear anodized 7075 Aluminum. Height = 27 mm, Fluted Knob
- 5 Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- 6 Elastomer Guide: Non-clad FR4. Thickness = 0.75mm.
- 7 Socket Base Screw: Socket Head Cap Screw, alloy steel with black oxide finish, 0-80 Thread, 5/8" long.
- 8 Backing Plate: Black anodized 7075 Aluminum
- 9 Insulation Plate: FR4/G10
- 10 Latch: Black anodized 7075 Aluminum.

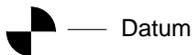
All Tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

	CG-BGA-4002 Drawing	Status: Released	Scale: -	Rev: A
	© 2007 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: Umer Qureshi		Date: 10/30/07
		File: CG-BGA-4002 Dwg	Modified:	

***Note: BGA pattern is not symmetrical with respect to the mounting holes.**



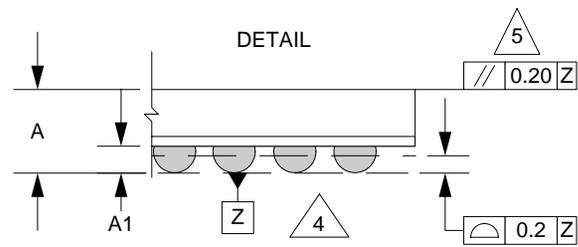
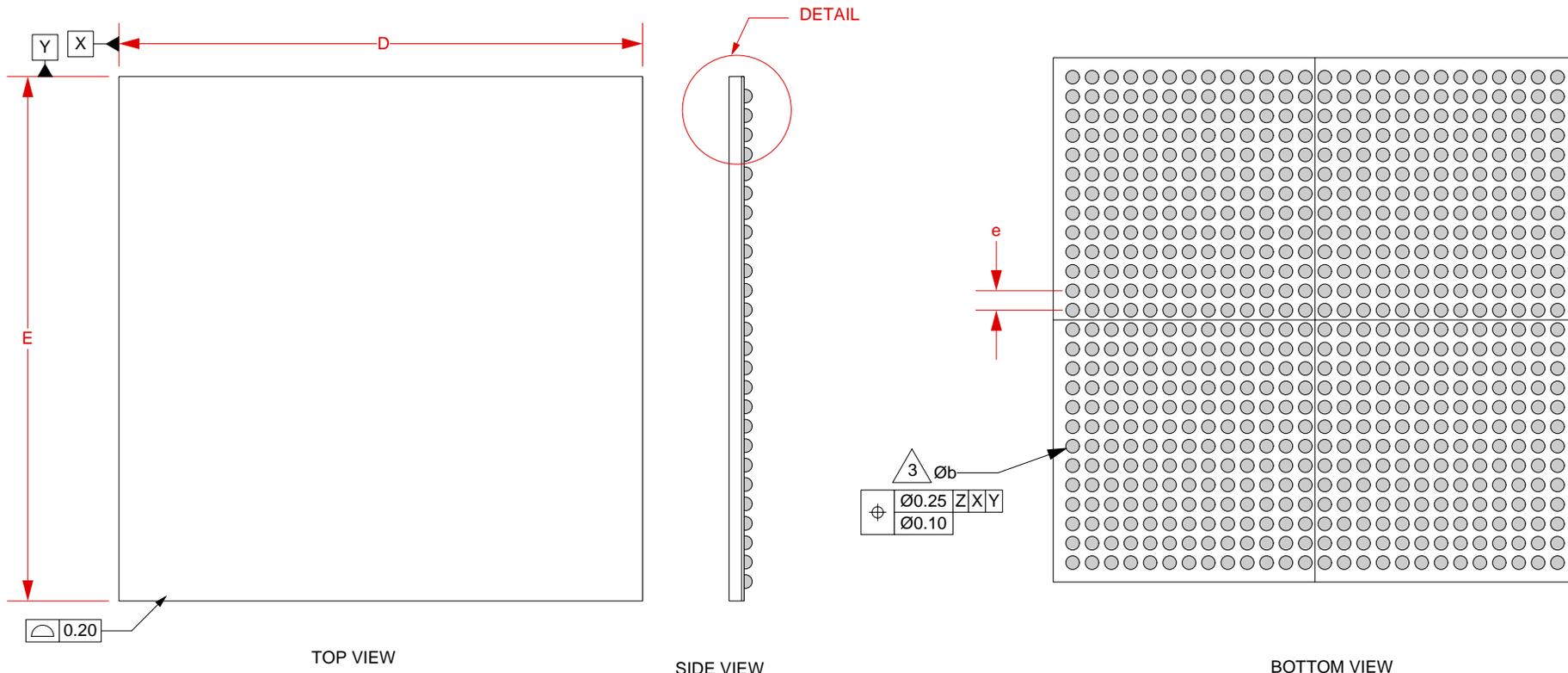
Target PCB Recommendations
Total thickness: 1.5mm min.
Plating: Gold or Solder finish



DXF DATA WILL BE PROVIDED

Recommended PCB Layout Tolerances:
±0.025mm [±0.001"] unless stated otherwise.

	CG-BGA-4002 Drawing	Status: Released	Scale: 3:1	Rev: A
	© 2007 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: Umer Qureshi		Date: 10/30/07
		File: CG-BGA-4002 Dwg	Modified:	



1. Dimensions are in millimeters.
 2. Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3. Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
 - 4. Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
 - 5. Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		2.5
A1	0.4	0.6
b		0.70
D	27.00 BSC	
E	27.00 BSC	
e	1.0 BSC	

26x26 Array

	CG-BGA-4002 Drawing	Status: Released	Scale: -	Rev: A
	© 2007 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com	Drawing: Umer Qureshi		Date: 10/30/07
		File: CG-BGA-4002 Dwg	Modified:	

